

Special Issue

Photonics in Asia

Message from the Guest Editors

In this Special Issue we cordially invite original contributions from authors in the various areas of photonics. Submission contributions include but are not limited to (1) growth, synthesis and characteristics of photonic micro- and nano-materials; (2) physics, fabrication, and characterization of photonic devices; (3) numerical simulation and modeling; (4) low-dimensional photonic devices and materials; (5) other novel functional photonic materials, structures, and devices and their applications.

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As the world of science becomes ever more specialized, researchers may lose themselves in the deep forest of the ever increasing number of subfields being created. This open access journal *Applied Sciences* has been started to link these subfields, so researchers can cut through the forest and see the surrounding, or quite distant fields and subfields to help develop his/her own research even further with the aid of this multi-dimensional network.

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